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Product Change Notice (PCN)

October 1st, 2025

PCN EIC-1161 Additional Epoxy Mold Compound Qualification for Power SIP package devices

Detailed Description of Change

Littelfuse IXYS Integrated Circuits Division (ICD) would like to inform you about the qualification of an additional EMC (Epoxy Mold Compound) to ensure security of supply for the part numbers summarized in the table below.

The affected part numbers listed below are fully qualified in accordance with established performance and reliability criteria.

Affected List	
CPC1705Y	
CPC1706Y	
CPC1726Y	
CPC1906Y	
CPC1916Y	
CPC1926Y	
CPC1973Y	
CPC1981Y	
CPC1983Y	CPC1983YE
CPC1966Y	CPC1966YX6
CPC1976Y	CPC1976YX6
CPC1984Y	
CPC1511Y	

Form, fit, function changes: None
Part number changes: None
Replacement products: N/A
Last time buy: N/A
Effective date: November 1st, 2025

The PCN number assigned to this action is **PCN EIC-1161** and must be referenced in any correspondence related to the change.

If you have any other questions or concerns, please contact your local Littelfuse sales representative or Product Manager below for further assistance.

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